

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs |  | User Part Number  |                                   |           |            |           |  |  |
|---|--|---|-----------------------------------|-----------|------------|-----------|--|--|
|   |  | BZX58550-C9V1   |                                   |           |            |           |  |  |
|   |  | Part Description  |                                   |           |            |           |  |  |
|   |  | Nexperia DHAM   | Zener                             |           |            |           |  |  |
|   |  | SMD package   |                                   |           |            |           |  |  |
| Test  |  | Test Conditions   | Duration                          | # Lots    | # Quantity | # Rejects |  |  |
|   | <b>TEST</b> Pre- and Post-Stress Electrical Test         | T. I. 25.00   | 21/2                              |           |            |           |  |  |
| # 1   | Electrical Test  | Tamb = 25 °C  | N/A                               | see below | all parts  | see below |  |  |
| # 2   | <b>PC</b> Preconditioning                                | JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering                   | 24 hours<br>168 hours<br>3 cycles | 1514      | 64430      | 0         |  |  |
| # 5   | HTRB<br>High Temperature Reverse<br>Bias                 | MIL-STD-750-1<br>M1038 Method A<br>Tj = Tjmax, VR = 80 % of rated reverse<br>voltage          | 1000 hours                        | 250       | 11400      | 0         |  |  |
| # 5c  | SSOP Steady State Operational                            | MIL-STD-750-1<br>M1038 Method B<br>Tj = Tjmax, Iz = 100% of max. datasheet<br>reverse current | 1000 hours                        | 44        | 1920       | 0         |  |  |
| # 7   | <b>TC</b><br>Temperature Cycling                         | JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C   | 500 cycles                        | 311       | 14080      | 0         |  |  |
| # 8 <b>or</b>   | <b>UHAST</b><br>Unbiased HAST                            | JESD22-A118<br>Tamb = 130 °C, RH = 85 %   | 96 hours                          | 311       | 14080      | 0         |  |  |
| # 8a  | <b>AC</b><br>Autoclave                                   | JESD22-A102<br>Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia)                    |                                   |           |            |           |  |  |
| # 9   | <b>H3TRB</b> High Humidity High Temperature Reverse Bias | JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage $^{[1]}$               | 1000 hours                        | 311       | 14080      | 0         |  |  |
| # 10  | IOL Intermittent Operating Life                          | MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj$ = 100 °C            | 333 hours                         | 312       | 14120      | 0         |  |  |
| # 20  | <b>RSH</b><br>Resistance to Solder Heat                  | JESD22-A111<br>260 °C ± 5 °C  | 10 s                              | 269       | 8070       | 0         |  |  |
| # 21  | <b>SD</b><br>Solderability                               | J-STD-002   |                                   | 222       | 6660       | 0         |  |  |

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia  |            |          |         |                    |            |
| DHAM      | Zener      | 11400    | 0       | 0,37               | 2,68E+09   |

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